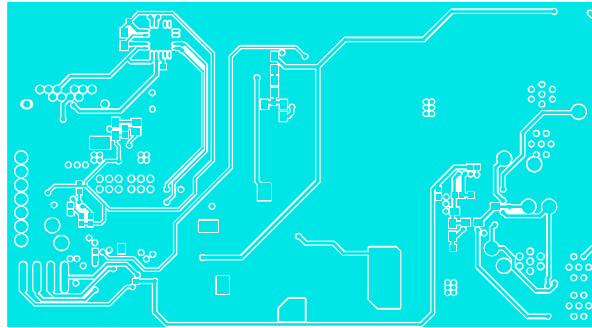
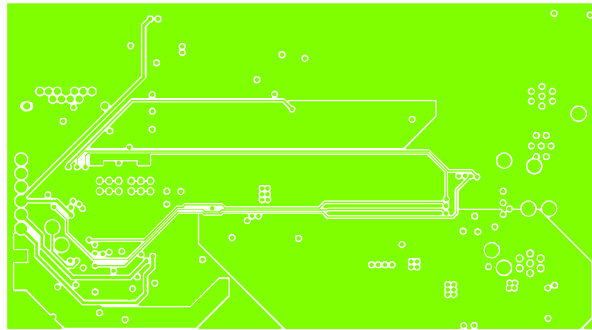
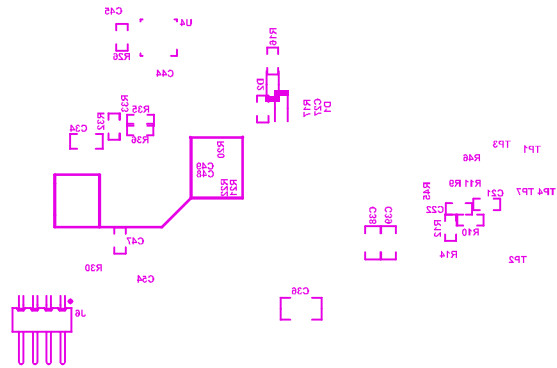


Top Layer

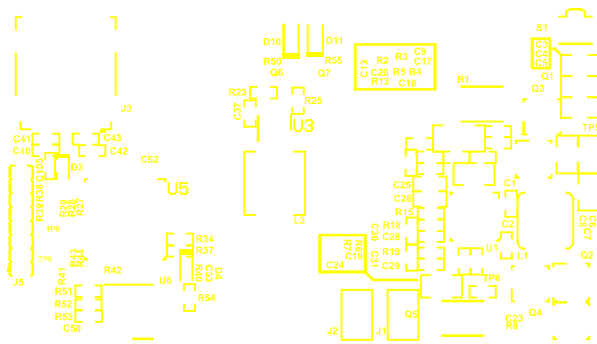


Bottom Layer

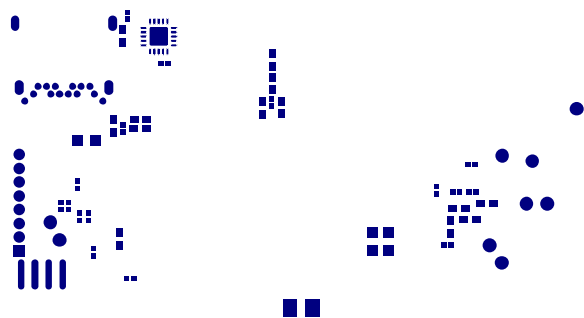


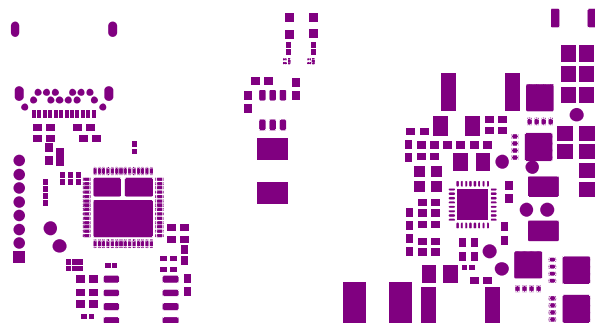


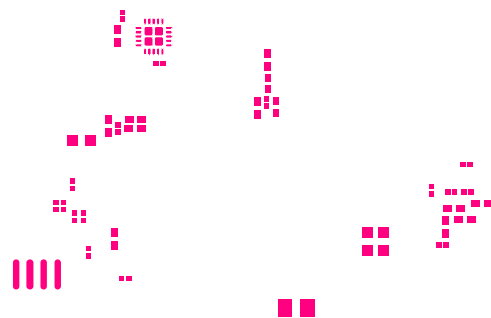
Bottom Overlay



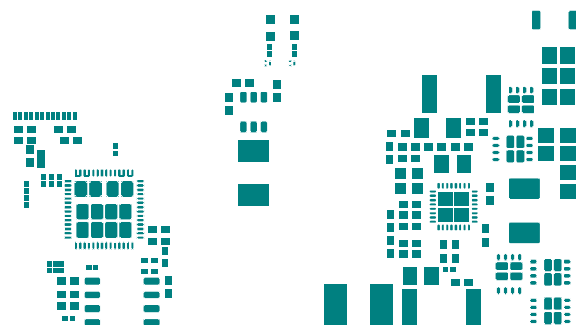
Top Overlay



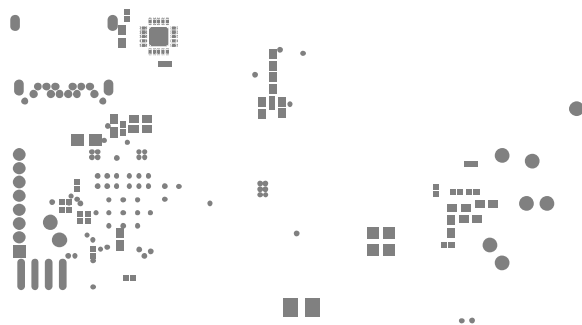




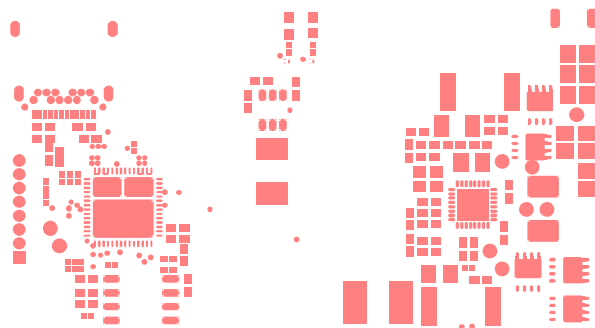
Bottom Paste



Top Paste



Bottom Solder



Top Solder

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